

A

Pin heatsinks

B

C

D

E

F

G

H

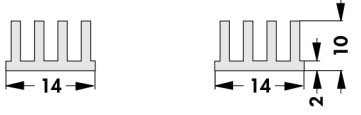

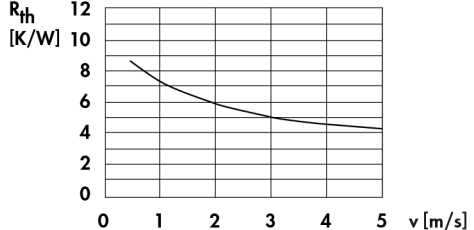
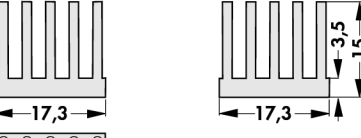
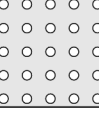
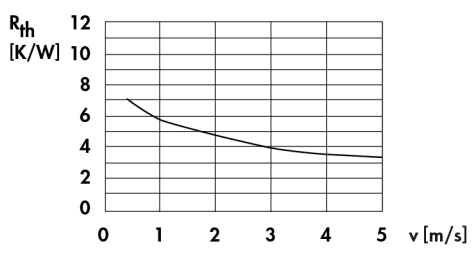
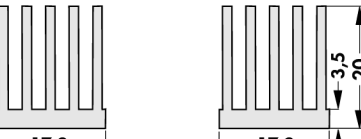

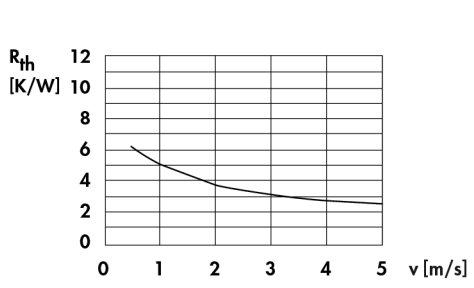
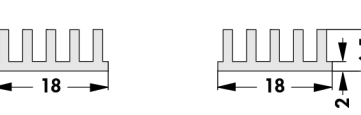

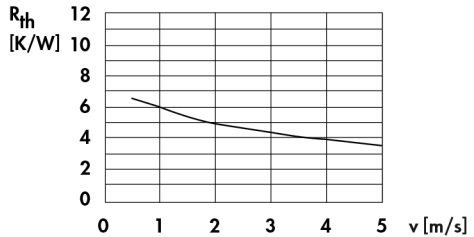
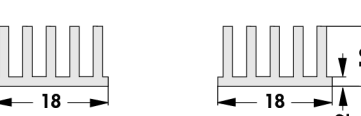

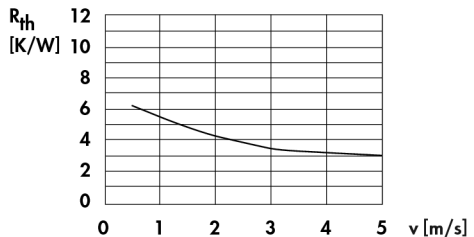

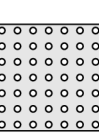
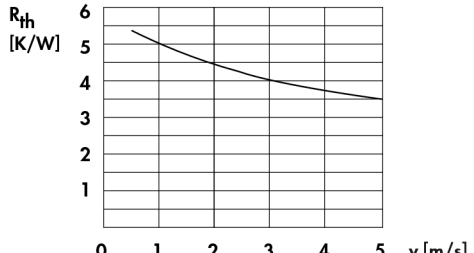
I

K

L

M

N

art. no. ICK S 14 x 14 x 10 WLF ... 14 x 14 weight: 1.9 g	 	
art. no. ICK S 17 x 17 x 15 WLF ... 17 x 17 weight: 4.7 g	 	
art. no. ICK S 17 x 17 x 20 WLF ... 17 x 17 weight: 5.6 g	 	
art. no. ICK S 18 x 18 x 6,5 WLF ... 18 x 18 weight: 2.5 g	 	
art. no. ICK S 18 x 18 x 10 WLF ... 18 x 18 weight: 3.1 g	 	
art. no. ICK S 25 x 25 x 6,5 WLF ... 25 x 25 weight: 4 g	 	

B 17

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7